

ULTRASONIC BONDING METHOD AND DEVICEABSTRACT OF THE DISCLOSURE

In an ultrasonic bonding method that bonds a material to a bonding surface by the application of ultrasonic vibration, both side faces of the material in the direction of ultrasonic vibration are clamped by an application member that applies a predetermined ultrasonic vibration, and by a clamping member. The clamping member is synchronously vibrated by ultrasonic vibration transmitted through the material from the application member, and the material is bonded to the bonding surface while being pressed against the application member and against the bonding surface. In this method, high bonding quality can be achieved by efficiently transmitting ultrasonic vibration from the application member to a material to be bonded, and the material can be prevented from tilting, cracking, chipping, or the like without being subjected to a special working operation, for example, forming of a chamfered portion.